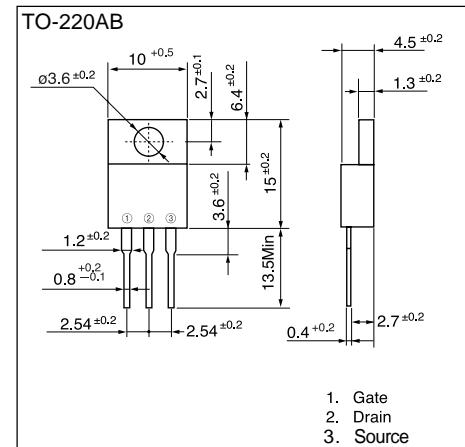


**N-CHANNEL SILICON POWER MOS-FET****■ Features**

- High speed switching**
- Low on-resistance**
- No secondary breakdown**
- Low driving power**
- Avalanche-proof**

**■ Applications**

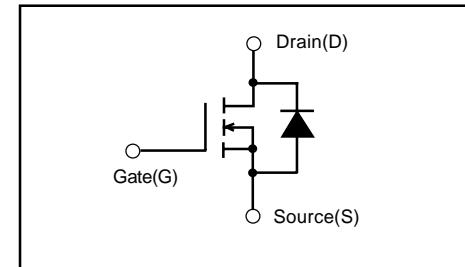
- Switching regulators**
- UPS (Uninterruptible Power Supply)**
- DC-DC converters**

**■ Maximum ratings and characteristic Absolute maximum ratings**

● (Tc=25°C unless otherwise specified)

Item	Symbol	Rating	Unit
Drain-source voltage	VDS	100	V
Continuous drain current	Id	±50	A
Pulsed drain current	Id(puls)	±200	A
Gate-source voltage	VGS	±30	V
Maximum Avalanche Energy	EAV*1	464	mJ
Max. power dissipation	Ta=25°C Pd	1.67	W
	Tc=25°C Pd	135	W
Operating and storage temperature range	Tch Tstg	+150 -55 to +150	°C

\*1 L=298μH, Vcc=24V

**■ Equivalent circuit schematic****● Electrical characteristics (Tc =25°C unless otherwise specified)**

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	V(BR)DSS	Id=1mA VGS=0V	100			V
Gate threshold voltage	VGS(th)	Id=1mA VDS=VGS	2.5	3.0	3.5	V
Zero gate voltage drain current	Idss	VDS=100V VGS=0V	1	100	100	μA
		Tch=25°C Tch=125°C	0.1	0.5	0.5	mA
Gate-source leakage current	IGSS	VGS=±30V VDS=0V	10	100	100	nA
Drain-source on-state resistance	RDS(on)	Id=25A VGS=10V	20	25	25	mΩ
Forward transconductance	gfs	Id=25A VDS=25V	16.0	32.0	32.0	S
Input capacitance	Ciss	VDS=25V	3200	4800		pF
Output capacitance	Coss	VGS=0V	760	1140		
Reverse transfer capacitance	Crss	f=1MHz	230	345		
Turn-on time ton	td(on)	Vcc=48V Id=50A	23	35		ns
	tr	VGS=10V	130	195		
Turn-off time toff	td(off)	Rgs=10Ω	110	165		ns
	tf		65	100		
Avalanche capability	Iav	L=100μH Tch=25°C	50			A
Diode forward on-voltage	VSD	If=50A VGS=0V Tch=25°C		0.97	1.46	V
Reverse recovery time	trr	If=50A VGS=0V		150		ns
Reverse recovery charge	Qrr	-di/dt=100A/μs Tch=25°C		0.80		μC

**● Thermal characteristics**

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	Rth(ch-c)	channel to case			0.93	°C/W
	Rth(ch-a)	channel to ambient			75.0	°C/W

## ■ Characteristics

